

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

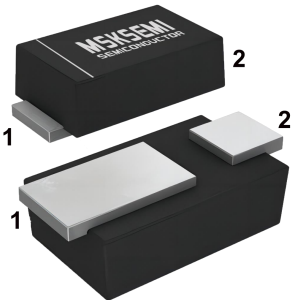


RB160VAM-40TR

Product specification

FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Low power loss,high efficiency.
- For use in low voltage high frequency inverters,free wheeling,and polarity protection applications.
- Guardring for over voltage protection.
- High temperature soldering guaranteed:260°C/10 seconds at terminals

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
		
SOD-323HE		

MAXIMUM RATINGS(Ta = 25℃)

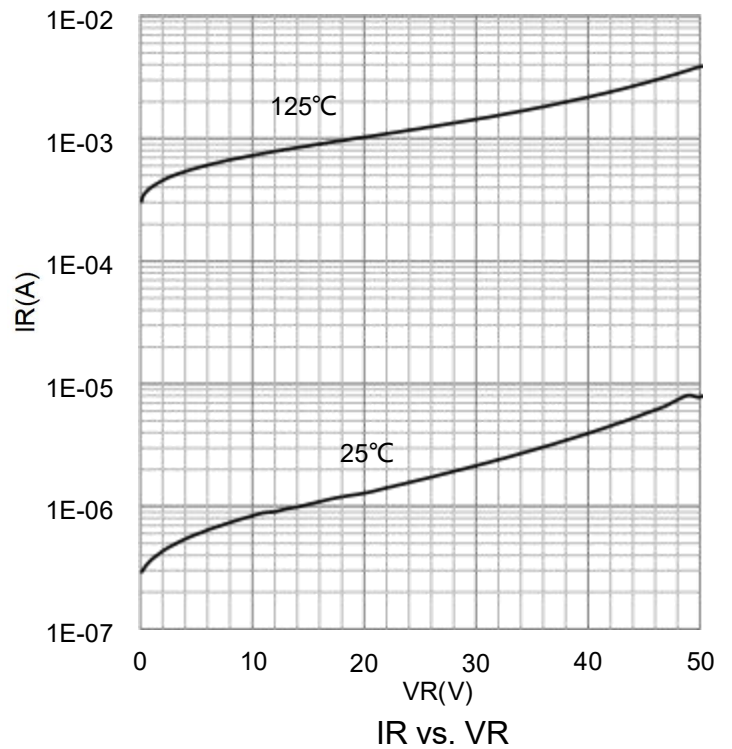
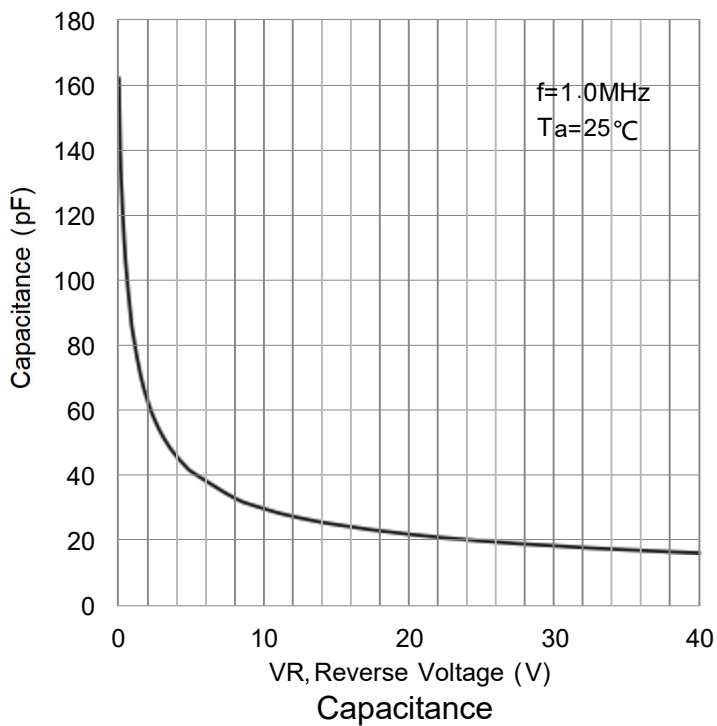
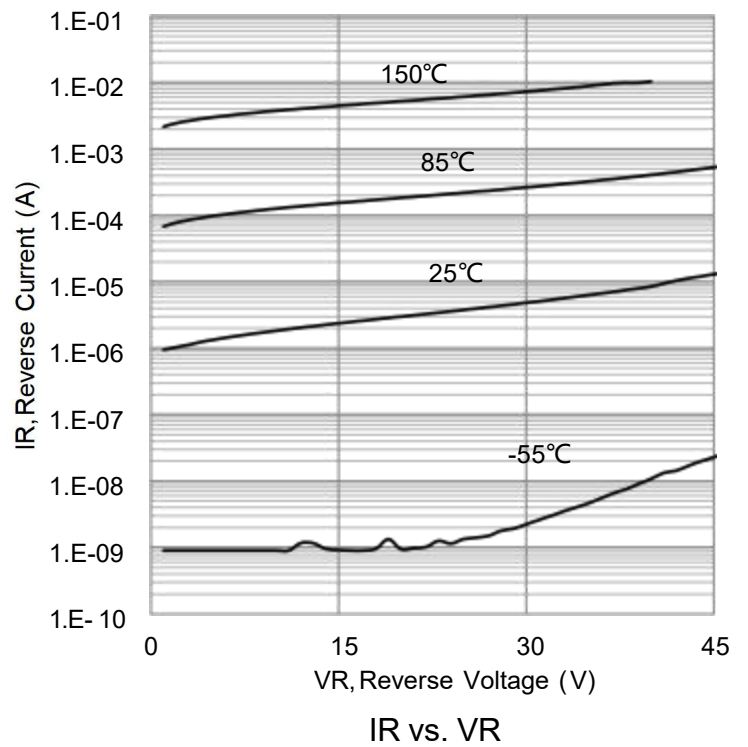
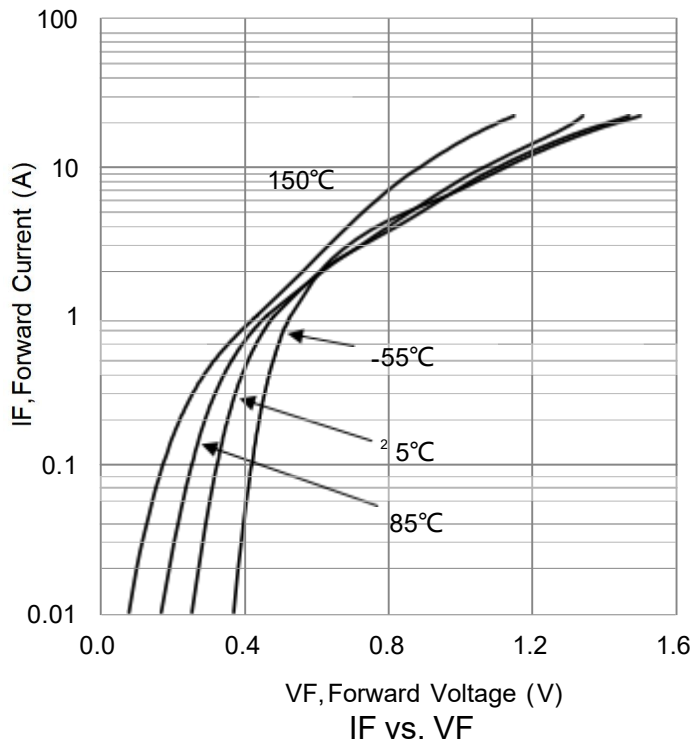
Parameter	Symbol	Limits	Unit
Maximum repetitive peak reverse voltage	VRRM	40	V
Maximum RMS voltage	VRMS	28	V
Maximum DC blocking voltage	VDC	40	V
Maximum average forward rectified current at TC =75 ℃	IF(AV)	1	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	15	A
Typical thermal resistance (Note 1)	RθJA	210	℃/ W
	RθJL	70	
Operating junction temperature range	TJ	-55 ~ +150	℃
storage temperature range	TSTG	-55 ~ +150	℃

Note:1.8.0mm²(.013mmthick)landareas

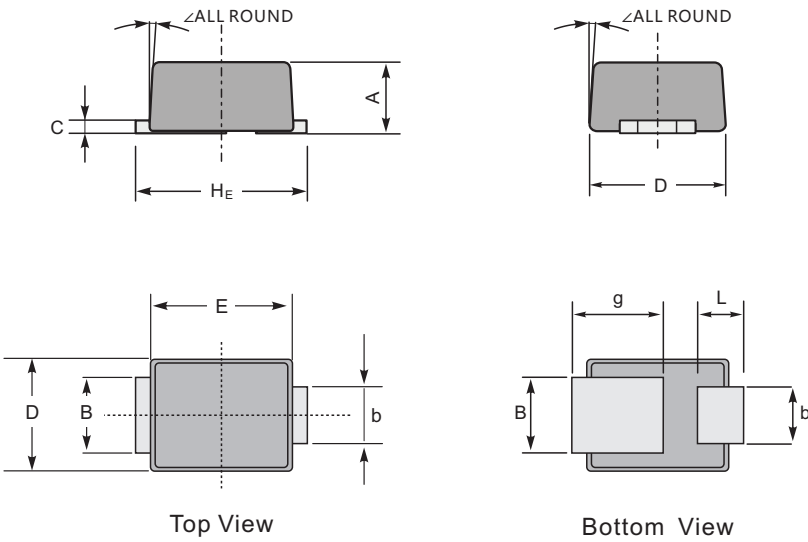
ELECTRICAL CHARACTERISTICS (Ta= 25℃)

Characteristic	Symbol	Min	Typ	Max	Unit
Maximum instantaneous forward (IF =0.7 A, TJ = 25 ℃) (IF = 1.0 A, TJ = 25 ℃)	VF	- -	- -	0.46 0.6	V
Maximum DC reverse current at rated DC blocking voltage TA = 25 ℃ TJ = 125 ℃	IR	- -	5 2.5	50 60	uA mA
Typical junction capacitance at 4 . 0V , 1MHz	CJ	-	50	-	pF

ELECTRICAL CHARACTERISTICS CURVES



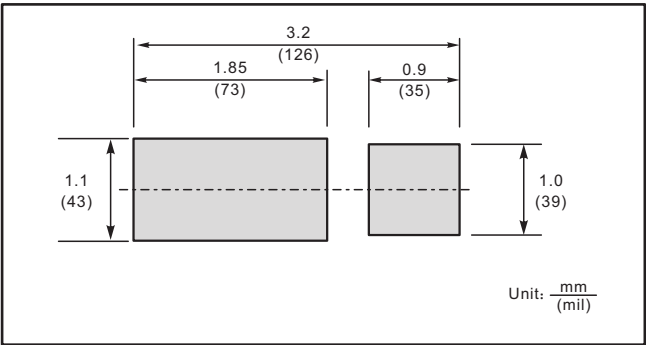
OUTLINE AND DIMENSIONS



UNIT		A	b	B	C	D	E	HE	g	L	∠
mm	max	0.77	0.75	0.95	0.20	1.45	2.3	2.7	1.55	0.8	12°
	min	0.57	0.45	0.65	0.10	1.25	2.1	2.3	1.1	0.4	
mil	max	30	30	37	8	57	91	106	61	31	
	min	22	18	26	4	49	83	91	43	16	

SOLDERING FOOTPRINT

RECOMMENDED PAD



REEL SPECIFICATION

P/N	PKG	QTY
RB160VAM-40TR	SOD-323HE	3000

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